1.6x0.8mm SMD CHIP LED LAMP

Part Number: APHM1608SURCK

Hyper Red

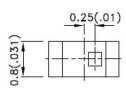
Features

- 1.6mmx0.8mm SMT LED, 0.45mm max. thickness.
- Low power consumption.
- Wide viewing angle.
- · Ideal for backlight and indicator.
- · Various colors and lens types available.
- Package: 2000pcs / reel.
- Moisture sensitivity level : level 3.
- RoHS compliant.

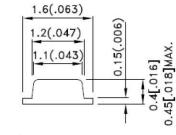
Description

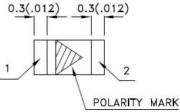
The Hyper Red source color devices are made with Al-GaInP on GaAs substrate Light Emitting Diode.

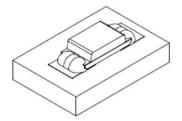
Package Dimensions











- All dimensions are in millimeters (inches).
 Tolerance is ±0.1(0.004*) unless otherwise noted.
 Specifications are subject to change without notice.
- 4. The device has a single mounting surface. The device must be mounted according to the specifications.





Selection Guide

Part No.	Dice	Lens Type	lv (mcd) [2] @ 20mA		Viewing Angle [1]
			Min.	Тур.	201/2
APHM1608SURCK	Hyper Red (AlGaInP)	WATER CLEAR	70	220	120°

- Notes:
 1. 61/2 is the angle from optical centerline where the luminous intensity is 1/2 the optical centerline value.
 2. Luminous intensity/ luminous Flux: +/-15%.

Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Typ.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Hyper Red	650		nm	I=20mA
λD [1]	Dominant Wavelength	Hyper Red	630		nm	I=20mA
Δλ1/2	Spectral Line Half-width	Hyper Red	28		nm	I==20mA
С	Capacitance	Hyper Red	35		pF	VF=0V;f=1MHz
V _F [2]	Forward Voltage	Hyper Red	1.95	2.5	V	I=20mA
IR	Reverse Current	Hyper Red		10	uA	V _R =5V

- Notes: 1.Wavelength: +/-1nm. 2. Forward Voltage: +/-0.1V.

Absolute Maximum Ratings at TA=25°C

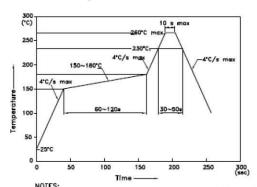
Parameter	Hyper Red	Units	
Power dissipation	75	mW	
DC Forward Current	30	mA	
Peak Forward Current [1]	185	mA	
Reverse Voltage	5	٧	
Operating Temperature	-40°C To +85°C		
Storage Temperature	-40°C To +85°C		

Note: 1. 1/10 Duty Cycle, 0.1ms Pulse Width.

APHM1608SURCK

Reflow soldering is recommended and the soldering profile is shown below. Other soldering methods are not recommended as they might cause damage to the product.

Reflow Soldering Profile For Lead-free SMT Process.



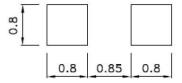
NOTES:

1. We recommend the reflow temperature 245°C(+/-5°C). The maximum soldering temperature should be limited to 260°C.

2.Don't cause stress to the epoxy resin while it is exposed to high temperature.

3. Number of reflow process shall be 2 times or less.

Recommended Soldering Pattern (Units: mm; Tolerance: ± 0.1)



Tape Dimensions (Units: mm)

